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K. TATSUMI et al.

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U. S. PATENT DOCUMENTS

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS

EXAMINER INITIAL		AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
AC		"Micro-ball Bump Technology For Fine-pitch Interconnections", Shimokawa K; Tatsumi K; Hashino E; Ohzeki Y; Konda M; Kawakami Y; Conference Proceedings Article 1 st 1997 IEMT/IMC Symposium (IEEE Cat. No. 97CH36059), Proceedings of 1997 First International Electronic Manufacturing Technology (IEMT) IMC Symposium, Tokyo, Japan, 16-18 April 1997; ISBN 0-7803-4235-6, pages 105-109.

EXAMINER	<i>Alonso Chambliss</i>	DATE CONSIDERED	5/16/03
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

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